

Application No.: 10/055,560

Docket No.: JCLA8532-R

In The Claims:

Claims 1-241. (canceled)

242. (new) A chip packaging method comprising:
joining a die and a substrate;
after said joining said die and said substrate, depositing a passive device over said
substrate; and
separating said substrate.

243. (new) A chip packaging method comprising:
joining a die and a substrate, said die having a top surface at a horizontal level;
after said joining said die and said substrate, depositing a passive device over said
horizontal level; and
separating said substrate.

244. (new) A chip packaging method comprising:
providing a die having a top surface at a horizontal level;
depositing a passive device over said horizontal level; and
depositing a trace over said horizontal level and extends to a place under which said die
does not exist.